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(54) **SCALABLE COOLING ARCHITECTURE
FOR LIQUID AND AIR INTAKE AIR
COOLING MODULES**

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(57) **ABSTRACT**

Systems, devices, and methods for providing liquid and air cooling for IT components in a facility is disclosed. The system includes a module comprising at least one dry cooler and at least one liquid heat exchange device. The module includes a primary cooling loop with the at least one dry cooler and the at least one liquid heat exchange device. The system also includes a secondary loop that includes the at least one liquid heat exchange device and one or more IT units in the facility. The system includes a path for air cooling the one or more IT units in the facility that includes an air intake from outside the facility that supplies air for cooling the one or more IT units. The method includes adjusting a first valve controlling liquid flow in a primary loop and adjusting a second valve controlling liquid flow in a secondary loop.

